

FIGURE 1A

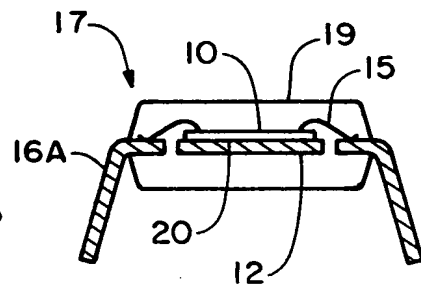


FIGURE 1B

**PROVIDING A CONVENTIONAL SEMICONDUCTOR DIE  
AND LEADFRAME, STEP A.**

**DISPENSING AN INSTANT CURING ADHESIVE  
MATERIAL ON THE LEADFRAME (OR ALTERNATELY ON  
THE DIE), STEP B.**

**PLACING THE DIE IN CONTACT WITH THE ADHESIVE  
MATERIAL, STEP C.**

**POLYMERIZING THE ADHESIVE MATERIAL TO FORM A  
CURED ADHESIVE LAYER AND BOND THE DIE TO THE  
LEADFRAME, STEP D.**

FIGURE 2

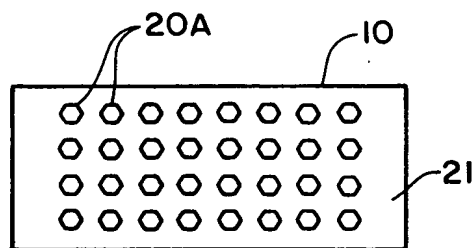


FIGURE 3A

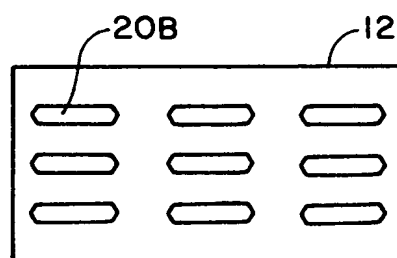


FIGURE 3B

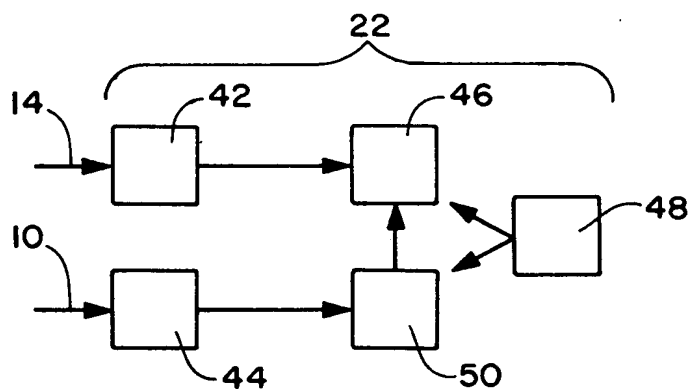


FIGURE 4

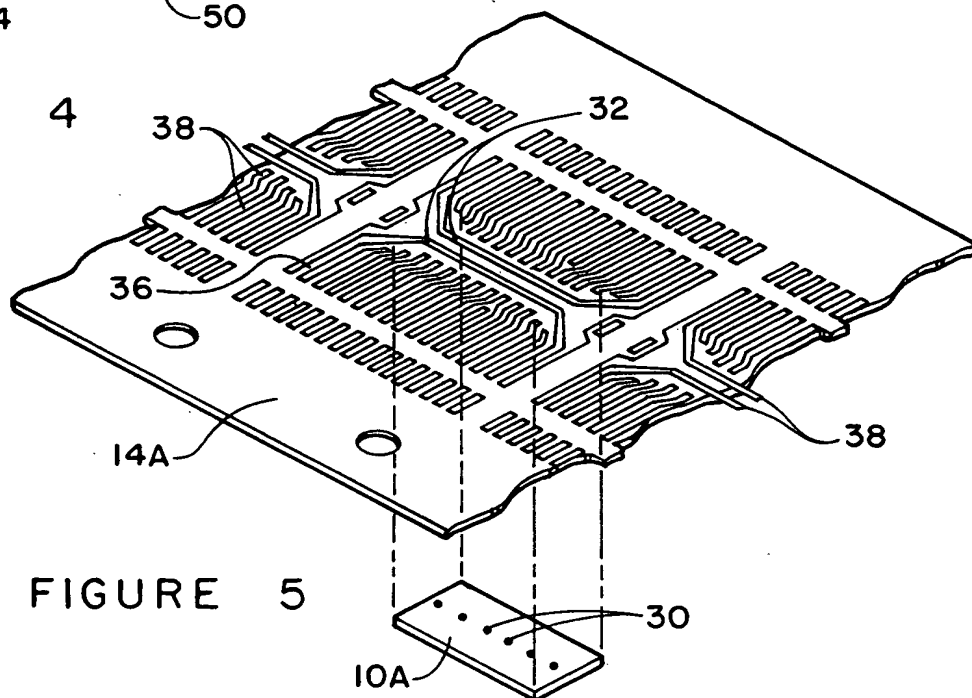


FIGURE 5

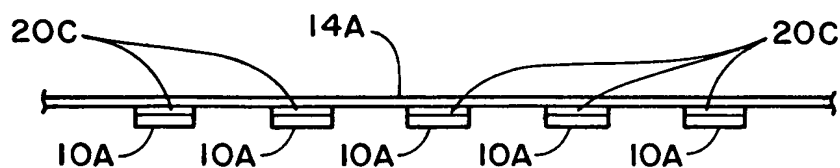


FIGURE 6